

# IB prototyping activity



## Prototyping in 2026 with ER2 (pad) wafer:

- what is going to be available for SVT:
  - ✓ **24 ER2 pad wafers** (w/ pads w/o sensor)
  - ✓ **12 ER2 wafers** (w/ pads & sensor)
- IB HB prototype with ER2 pad wafers:
  - ✓ full proto (including FPCs) suited for mechanical tests
  - ✓ min required pieces (not considering failures/breakings):
    - 2 x 3 segments + 2 x 4 segments + 4 x 5 segments = **8 pad wafers**
    - ideally 2 HBs (mechanical matching tests) → 2 x 8 = **16 pad wafers** with given segments distribution
- IB HB prototype with ER2 wafers:
  - ✓ full proto (including FPCs) suited for mechanical/cooling/electrical post-assembly tests
  - ✓ suitable also for powering/DAQ/DCS development on close-to-final setup system
  - ✓ min required pieces (not considering failures/breakings and sensor yield): **8 wafers**

